

Features

- High compressibility
- Pump out resistance
- Good adhesion
- Long term stability
- Siloxane Volatiles D4% to D200%

Description

MP008797 is a dispensible non silicone thermal putty

Specification

Characteristic	Test Method	Value
Colour	Visual	Grey
Thermal conductivity W/m K	ASTM D5470	3.5
Density g/cm ³	ASTM D792	2.8
Application temperature (°C)	ASTM D5470	-40 to +125
Bond line thickness, typical min, mm	ASTM D374	0.05
Dielectric breakdown, kV/mm	ASTM D419	>5
Flow rate (g/min), 90psi/2mm nozzle @ 25°C		50
Volume resistivity (Ohms.cm)	ASTM D257	> 10 ¹¹
Durability, high storage baking, (hrs)	JESD22-A103	1000

Part Number Table

Description	Part Number
Thermal Interface Putty, Non-Silicone, 3.5W/mK, 50ml	MP008797

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